

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	69	sarvar.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 18:38
S2	0	S1 and reflow	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:14
S3	0	S1 and interpolat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:14
S4	296	whalley.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:16
S5	0	S4 and reflow	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:16
S6	22746	solder same reflow	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:16
S7	1988	S6 and (simulat\$4 or model\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:16
S8	23	S7 and interpolat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:17
S9	2113938	(circuit surface) same mount\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:18

S10	164099	S9 and (simulat\$4 or model\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:18
S11	4774	S10 and interpolat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:19
S12	207	S11 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 13:19
S13	120	S12 and thermal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 14:30
S14	1	("6386277").PN.	USPAT; USOCR	OR	OFF	2006/08/30 18:55
S15	440	703/17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 18:55
S16	5	S15 and (surface same mount)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 18:55
S17	1034	circuit and (simulat\$3 same solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 13:03
S18	4213	"I2" and interpolat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 12:47
S19	13	S17 and interpolat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 12:48
S20	1327	S18 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 12:48

S21	636	S17 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 12:48
S22	60	S21 and simulat\$3.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 12:49
S23	33	S22 and @ad< "20030130"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 12:49
S24	89	circuit and (simulat\$3 same reflow same solder \$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 13:41
S25	0	("2004/0186702").URPN.	USPAT	OR	OFF	2007/07/19 13:05
S26	114	(simulat\$3 same reflow same solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/19 13:41
S27	5	"165694".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/21 14:05
S28	1	converification.ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 18:53
S29	2	"5325505".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:16
S30	52	("5325505").URPN.	USPAT	OR	OFF	2007/08/04 19:42
S31	4177	data same storage same simulation	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 19:43

S32	52	("5325505").URPN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 19:42
S33	52	("5325505").URPN.	USPAT	OR	OFF	2007/08/04 19:42
S34	1884	S31 and performance	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 19:43
S35	1134	S34 and @ad<"20030130"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 19:43
S36	34	S35 and ((data near2 storage) and simulation). ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 19:43
S37	16374	reflow adj3 solder\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:16
S38	24097	reflow near3 solder\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:25
S39	341	S38 and simulation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:16
S40	22	S38 and (simulation same (reflow and solder\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:17
S41	87	S38 and (simulation same solder\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:17

S42	13	("5036479" "5060276" "5389764").PN. OR ("5562243").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/04 20:19
S43	7144	(reflow near3 solder\$3). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:03
S44	5	S43 and simulat\$3.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 20:41
S45	2	((("4180199") or ("5003160"))).PN.	USPAT; USOCR	OR	OFF	2007/08/04 20:41
S46	79	((((surface near2 mount) (reflow near3 solder\$3)) and (simulat\$3 or model \$3)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:05
S47	77	S46 not S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:04
S48	77	S47 not S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:04
S49	17688	((surface near2 mount) (reflow near3 solder\$3)). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:06
S50	276	S49 and ((mount\$3 solder \$3) same (simulat\$3 model \$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:06
S51	203	S50 and @ad< "20030130"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:07
S52	165	S51 not S48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/04 21:07

S53	0	(print\$3 and circuit and assembl\$3 and simulat*)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:15
S54	19550	(print\$3 and circuit and assembl\$3 and simulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:15
S55	57	(print\$3 and circuit and assembl\$3 and simulat\$3). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:20
S56	19937	(circuit and simulat\$3).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:21
S57	98	S56 and (printed same circuit same assembl\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:22
S58	1	S57 and reflow	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:22
S59	0	S57 and (printing with mounting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:23
S60	0	S57 and (printing same mounting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:23
S61	2	S56 and (printing and reflow and mounting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/29 11:23

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